



No: CESI2024EV/GHG0008R0L

组织温室气体排放核查声明

责任方名称及地址

中芯京城集成电路制造（北京）有限公司

北京市北京经济技术开发区亦庄新城 0606 街区 YZ00-0606-0001 地块

核查范围

位于北京市北京经济技术开发区

亦庄新城 0606 街区 YZ00-0606-0001 地块

中芯京城集成电路制造（北京）有限公司范围内
与集成电路制造相关的温室气体排放与清除。

核查准则: ISO14064-1: 2018;

保证等级: 合理保证等级

GHG 报告书: 《中芯京城集成电路制造（北京）有限公司 2023 年度
温室气体盘查报告书》

覆盖时间段: 2023 年 01 月 01 日-2023 年 12 月 31 日

排放的 GHG: ■CO₂ ■CH₄ ■N₂O ■NF₃ ■HFC_s ■PFC_s ■SF₆

温室气体排放总量: 268941.56 tCO₂e 其中:

(排放类别及排放量, 详见附件)

经依据 ISO14064-3: 2019 核查, 北京赛西认证有限责任公司认为:
中芯京城集成电路制造（北京）有限公司陈述的 GHG 报告书实质
性地正确, 并且公正地表达了 GHG 数据和信息; 该陈述系根据有关 GHG
量化、监测和报告的国际标准编制。

核查信息详见《GHG 核查报告》(No. 2024-GHG-0044-R1/01)

发布日期: 2024 年 1 月 17 日

换发日期: 2024 年 6 月 20 日

总经理:

韩强



中国认可
环境信息
ENVIRONMENTAL INFORMATION
CNAS W006-EI

北京赛西认证有限责任公司

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No: CESI2024EV/GHG0008ROL

组织温室气体排放核查声明附件

责任方名称及地址

中芯京城集成电路制造（北京）有限公司

北京市北京经济技术开发区亦庄新城 0606 街区 YZ00-0606-0001 地块

温室气体排放总量: 268941.56 tCO₂e 其中:

- (第 1 类) 直接 GHG 排放和清除: 9406.14 tCO₂e
- (第 2 类) 外部输入能源所产生的间接排放: 118204.73 tCO₂e
- (第 3 类) 运输所产生的间接温室气体排放: 352.03 tCO₂e
- (第 4 类) 组织所用产品产生的间接温室气体排放: 140978.66 tCO₂e
- (第 5 类) 与组织产品使用相关的间接温室气体排放: / tCO₂e
- (第 6 类) 其他源产生的间接温室气体排放: / tCO₂e

本页为证书附页，应与证书主页同时使用





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GHG EMISSIONS VERIFICATION STATEMENT

MANUFACTURER AND ADDRESS

SEMICONDUCTOR MANUFACTURE BEIJING CORPORATION

Land YZ00-0606-0001, Block 0606, Yizhuang New Town, Beijing Economic-Technological Development Area, Beijing, P.R China

SCOPE OF VERIFICATION

GREENHOUSE GAS EMISSION AND REMOVAL ACTIVITIES RELATED TO INTEGRATED CIRCUIT MANUFACTURING WITHIN THE SCOPE OF SEMICONDUCTOR MANUFACTURE BEIJING CORPORATION LOCATED AT LAND YZ00-0606-0001, BLOCK 0606, YIZHUANG NEW TOWN, BEIJING ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA, BEIJING, P.R CHINA

STANDARDS AND TECHNICAL REQUIREMENTS

ISO 14064-1:2018

LEVEL OF ASSURANCE

Reasonable Level of Assurance

GHG ASSERTIONS

GHG inventory report of Semiconductor Manufacture Beijing Corporation (2023)

COVERING PERIOD

January 1, 2023 to December 31, 2023

GHG EMISSIONS

■ CO₂ ■ CH₄ ■ N₂O ■ NF₃ ■ HFCs ■ PFCs ■ SF₆

Total GHG emissions: 268941.56 tCO₂e

(SEE THE ANNEX OF GHG EMISSIONS VERIFICATION STATEMENT)

According to ISO 14064-3: 2019, CESI here confirms that:

The GHG statement provided by SEMICONDUCTOR MANUFACTURE BEIJING CORPORATION is materially correct and specifies the GHG data and information fairly. The GHG statement is prepared in accordance with the related International Standards on GHG quantification, monitoring and reporting.

The verification information could be found in the verification report of GHG (No. 2024-GHG-0044-R1/01).

ISSUE DATE: January 17, 2024

EXCHANGE DATE: June 20, 2024

Manager:



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CESI Certification Co., Ltd.



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ANNEX OF GHG EMISSIONS VERIFICATION STATEMENT

MANUFACTURER AND ADDRESS

SEMICONDUCTOR MANUFACTURE BEIJING CORPORATION

Land YZ00-0606-0001, Block 0606, Yizhuang New Town, Beijing Economic-Technological Development Area, Beijing, P.R China

Total GHG emissions: 268941.56 tCO₂e

Direct GHG emissions and removals: 9406.14 tCO₂e

Indirect GHG emissions from imported energy: 118204.73 tCO₂e

Indirect GHG emissions from transportation: 352.03 tCO₂e

Indirect GHG emissions from products used by organization: 140978.66 tCO₂e

Indirect GHG emissions associated with the use of products from the organization: / tCO₂e

Indirect GHG emissions from other sources: / tCO₂e

This page is attached to the certificate and
should be used at the same time as the certificate home page